



FULLY AUTOMATIC DICING MACHINE

AD3000T-PLUS

Fast, refined and innovative



TWIN Dicing concept with two opposing Spindles

World's smallest Dicing Machine

Achieved smallest footprint possible utilizing our own core technology. Size reduced down to 68% by comparison.

World's most efficient Dicing Machine

Delivering fast X-axis (Up to 1,000 mm/sec) and Y-axis (Up to 300 mm/sec) processing speed. Low Cost of ownership.

Introducing refined Graphic User Interface

Tokyo Seimitsu was the first to introduce TWIN Dicing Machine equipped with GUI and now realized easy operation.

Ease of maintenance

Widen front access door help improve routine maintenance with ease-of-maintenance in mind.



Tokyo Seimitsu has introduced Japan's first Wafer Dicing Machine, Model A-WD-75A in 1970 and tremendous contribution was made to success of Semiconductor industry with die separation process technology and its long term evolution with precision processing. Vast resource accumulated on Dicing Technology over four decades has enabled us to introduce next generation of Dicing machine, Model AD3000T-PLUS with latest technology in FLUIDIC ENGINEERING and ENERGY CONSERVATION to lead the world with Dicing technology.



TOKYO SEIMITSU

Main Features

- Optimized spacing by utilizing all components and optional unit well within the compartment**
- Standard Spindles up to 60,000 rpm**
(80,000 rpm as optional)
- High throughput**
1: X axis 1,000 mm/sec, Y axis 300 mm/sec, and Z axis 80 mm/sec
2: Two Optical Cutter-Set units
- 17" LCD touch panel and new GUI**
GUI(Graphical User Interface) with simple layout and large touch-buttons allow users' interactive operation
- Ease of maintenance**
Wide maintenance door and front side accessibility allows easy of routine maintenance



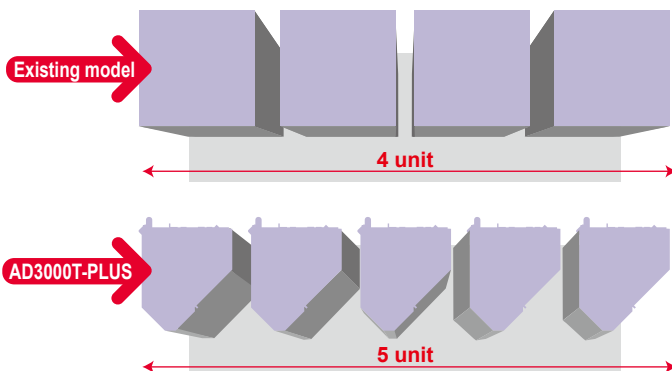
▲ NEW Graphic User Interface

Enhancement of optional function

- Dressing stage**
Equipped with two Dressing board (75 mm×75 mm size)
Available to dressing the blade of each spindle with a dedicated board.
- Air micrometer is mountable**
Available to non-contact measurement of tape thickness and wafer thickness.
High precision cutting position control is realized with reflecting to processing height.
- Available to control to high precision of cutting height**
The X, Y and Z axes are synchronously controlled during processing, realizing high precision processing that follows the waviness of the wafer.

Set up space

AD3000T/AD3000T-PLUS has succeeded with footprint reduction by comparison with existing model(A-WD-300TX)



仕様

Max. work size		Φ 305 mm
Max. number of frames		12 inch (SEMI G74-0699)
Spindle	Rotation	60,000 min-1 80,000 min-1 (Option)
	Max. blade diameter	Φ 60 mm (2-Inch) Φ 80 mm (3-Inch) (Option)
	Rated Output	1.8 KW
X axis	Available cutting range	310 mm
	Max. Speed	1,000 mm/s
Y1/Y2 axes	Available cutting range	310 mm
	Max. Speed	300 mm/s
	Resolution	0.078 μm
	Accuracy	0.002 mm / 310 mm
Z1/Z2 axes	Stroke	35 mm
	Resolution	0.002 μm
	Max. Speed	80 mm/sec
	Repeatability	0.001 mm
θ axis	Range of rotation	380°
Specification	Voltage	3 Phase AC200 to 220 V ±10 % (Transformer adoptable)
	Power consumption	6.0 kVA (MAX)
	Air pressure	0.55 ~ 0.7 MPa
	Avg. Air consumption	210 L/min (0.55 MPa)
	Avg. Clean air consumption	140 L/min
	Supply water pressure (Cutting water, and others)	0.3 ~ 0.5 MPa
	Supply water Max flow	Cutting water: 10.0 L/min Water curtain: 3.0 L/min Others: 0.6 L/min
	Cooling water pressure	0.3 ~ 0.5 MPa
	Cooling water flow	3.4 L/min (0.3 MPa)
	Required exhaust flow	5.0 m3/ min more
Size (W*D*H)		1,290 mm x 1,530 mm x 1,900 mm
Weight		1,360 kg

Maintenance

